

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Chakravarthi et al.

Docket No.: TI-33161

Serial No.: 10/020,813

Art Unit: 2813

Filed: 12/12/01

Examiner: Huynh, Yennhu

Title: Fabrication of Ultra Shallow Junctions From a Solid Source With Fluorine

Implantation

AMENDMENT UNDER 37 CFR 1.111

October 2, 2003

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

DER 37 CFR 1.111 MAILING CERTIFICATE UNDER	OCT -8 2003 TECHNOLOGY CENTER
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L besselv cartify that the above of	orrespondence is being deposited
with the U.S.	Postal Service onas First Class Mail in an
envelope addressed to: Commiss Alexandria, VA 22313-1450	sioner for Patents, P.O. Box 1450,
Karen Vertz Karen Vertz	10-2-03 Date

In response to the Office Action, dated 08/01/2003, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.